Analysis and Optimization of Thin Film Ferroelectric Phase Shifters

Robert R. Romanofsky
Glenn Research Center, Cleveland, Ohio

Fred W. Van Keuls
Ohio Aerospace Institute, Brook Park, Ohio

Joseph D. Warner, Carl H. Mueller, Samuel A. Alterovitz, and Felix A. Miranda
Glenn Research Center, Cleveland, Ohio

A. Haq Qureshi
Cleveland State University, Cleveland, Ohio

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ABSTRACT

Microwave phase shifters have been fabricated from (YBa$_2$Cu$_3$O$_{7-δ}$ or Au)/SrTiO$_3$ and Au/Ba$_x$Sr$_{1-x}$TiO$_3$ films on LaA1O$_3$ and MgO substrates. These coupled microstrip devices rival the performance of their semiconductor counterparts at Ku- and K-band frequencies. Typical insertion loss for room temperature ferroelectric phase shifters at K-band is ≈5 dB. An experimental and theoretical investigation of these novel devices explains the role of the ferroelectric film in overall device performance. A roadmap to the development of a 3 dB insertion loss phase shifter that would enable a new type of phased array antenna is discussed.

INTRODUCTION

Evolving high data rate communications systems demand greater attention to subtle aspects of information theory and electromagnetic engineering. As the ratio of signaling bandwidth to carrier frequency decreases, less familiar phenomenon enter into system performance. And, new coding techniques are pushing channel capacity ever closer to the Shannon limit [1]. Some of these effects are expected to become quite pronounced if the trend toward wide-band scanning phased array antennas and efficient high-speed modulators continues [2]. For example, in a phased array antenna inter-element spacing, the physical size of the array, and the steering vector can conspire to introduce pulse distortion from group delay, inter-symbol interference, and beam squinting [3,4]. And the operating point of the amplifiers can affect the bit error rate depending on the modulation type and the number of carriers. Naturally one wants the phased array to operate as efficiently as possible given power limitations and thermal management problems. This desire necessitates that the power amplifiers operate in a nonlinear region near saturation. Nonlinear effects cause amplitude-to-amplitude modulation (AM/AM) and amplitude-to-phase modulation (AM/PM) distortion. The net effect of AM/AM distortion is to alternately compress and expand the signal constellation. The net effect of AM/PM conversion is a rotation of the signal constellation [3]. In a receive array, the third order intercept of the low noise amplifiers largely determines inter-
modulation distortion and heat dissipation [5]. Phase shifters typically follow low noise amplifiers in a receive array and precede power amplifiers in a transmit array. Since the phase shifter’s insertion loss depends on its phase setting and since its switching action represents some finite time domain response, its potential contribution to bit error rate degradation cannot generally be ignored. There will always be some effects in any phase shift keyed (PSK) modulation system, to what degree depends on the steering vector update rate and data rate.

In 1963 Berry introduced a new class of antennas that utilized an array of elementary antennas as a reflecting surface [6]. The “reflectarray” has the potential to combine the best attributes of a gimbaled parabolic reflector, low cost and high efficiency, and a direct radiating phased array, vibration-free beam steering. A key advantage is the elimination of a complex corporate feed network. The reflectarray consists of a two-dimensional aperture characterized by a surface impedance and a primary radiator to illuminate that surface. The ferroelectric phase shifters described in this paper can be integrated with microstrip patch radiators to form a such a phase agile antenna [7]. Because the antenna elements and phase shifters can be defined using a two-step lithography process, the ferroelectric reflectarray holds promise to dramatically reduce manufacturing costs of phased array antennas and alleviates thermal management problems associated with microwave integrated circuit transmit arrays. (Note that while the devices to be described actually operate in the paraelectric regime slightly above the Curie temperature, it has become customary for workers in the field to still refer to the materials as ferroelectrics. This paper adheres to that convention.) A receive reflectarray has been designed at 19 GHz and is pictured in figure 1. The governing design assumption is a phase shifter insertion loss of 3 dB, about 40 percent better than we have consistently demonstrated from Ba,Sr$_{1-x}$TiO$_3$ films on LaAlO$_3$ and MgO substrates. A circular aperture was approximated arranging 177 subarrays as shown to improve the aperture efficiency.

Figure 1. A 2832 element 19 GHz ferroelectric reflectarray concept. The callout shows a 16 element subarray patterned on a 3.1×3.1 cm$^2$, 0.25 mm thick MgO substrate. The array diameter is 48.5 cm. The unit cell area is 0.604 cm$^2$ and the estimated boresight gain is 39 dB.
The array was designed to scan past a 45° angle with an inter-element spacing of 0.52 wavelengths. The callout shows 16 4-section phase shifters coupled to a square patch antenna with a 90° hybrid coupler. The phase shifter is terminated abruptly in an open circuit and is used in a reflection mode. One output of the coupler has an additional 45° microstrip extension to feed the orthogonal edges of the patch 90° out of phase. For right hand circular polarization, the phase shifter is attached to the left port of the coupler so the vertical edge of the patch receives the reflected energy with a 90° delay. While a triangular grid pattern permits the fewest elements per unit area, it was simpler to fit the phase shifters in a square unit cell. The governing assumption in the design is that a 3 dB insertion loss phase shifter can be consistently reproduced. Indeed the phase shifter performance drives the performance and cost of the entire array. Even with a 3 dB loss device, assuming a receiver noise figure of 2 dB, the system noise temperature exceeds 800 K. Because the phase shifter is inserted between the antenna terminals and the low noise amplifier, it has the same effect as a feed line with equivalent loss in the determination of noise. The array noise does not increase with the number of elements since the noise is non-coherent but the signal at each element is correlated [8]. Assuming an aperture efficiency of 70 percent and a scan loss that falls off as \( \cos^2 \theta \), the gain-to-noise temperature ratio (G/T) of the array is estimated at \( \approx 3.1 \text{ dB/K} \). If the phase shifter loss could be reduced to 2 dB, the number of elements would be cut approximately in half.

EXPERIMENT

The phase shifters analyzed here hold promise for reflectarray applications because they are compact, low-loss, and can be lithographed on the same surface as the radiating element. The designs used are based on a series of coupled microstriplines of length \( l \) interconnected with short sections of nominally 50 \( \Omega \) microstrip. The maximum coupled voltage occurs when the coupled sections are a quarter wavelength long (i.e. \( \beta l = 90^\circ \)). Bias up to 400 V is applied to the sections via printed bias-tees consisting of a quarter-wave radial stub in series with a very high impedance quarter-wave microstrip. A sketch of the coupled microstrip cross-section is show in figure 2. By concentrating the fields in the odd mode, the phase shift per unit length is maximized and by using the ferroelectric in thin film form the effects of high loss tangent are minimized. Selecting the strip spacing “\( s \)” involves a compromise among: minimizing insertion loss, simplifying lithography, and minimizing the tuning voltage.

\[
Y_1 = \frac{\varepsilon_0}{h_0} \quad \text{and} \quad Y_2 = \frac{\varepsilon_1}{h_1} \quad \text{represent the admittance looking in the positive and negative y direction, respectively, from the charge plane. The thickness of the ferroelectric layer is } h_1 \text{ while the host substrate has thickness } h_2.
\]

Figure 2. Cross-section of the coupled microstripline phase shifter showing the odd-mode electric field configuration. \( Y_1 \) and \( Y_2 \) represent the admittance looking in the positive and negative y direction, respectively, from the charge plane. The thickness of the ferroelectric layer is \( h_1 \) while the host substrate has thickness \( h_2 \).
A key advantage of this technology is the relatively large feature size. Active devices at the frequencies of interest here would necessitate submicron gate length GaAs FETs. The finest feature size associated with the coupled line phase shifters is the electrode separation $s$, typically $\approx 10 \mu m$. Whereas the GaAs FET performance is largely dictated by transconductance and hence carrier transit time across the gate region, the coupled line phase shifters are static devices. The electrode gap separation determines the degree of electromagnetic coupling and the dc potential required to tune the film. As a rule-of-thumb the cutoff frequency $f_c$ of a MESFET scales roughly with gate length ($l$) as $f_c = 9.4/l$ where the frequency is in GHz and $l$ is in microns. Hence the ferroelectric phase shifters have much larger feature sizes at a given frequency of operation and consequently much less demanding process requirements. The total phase shift can be increased by cascading coupled line sections. Each section is linked by a 50 Ohm or so microstrip jumper. A photograph of a 4-section phase shifter patterned on 0.5 mm MgO is shown in figure 3.

![Figure 3: A 4-element Ba,Sr$_{1-x}$TiO$_3$ phase shifter on 0.5 mm MgO. The circuit measures 1 cm x 1 cm. $l$=457 $\mu$m, $s$=10 $\mu$m, and $w$=56$\mu$m.](image)

These ferroelectric phase shifters are fabricated using standard lithography techniques. The “lift-off” processing recipe is straightforward. Starting with a clean substrate, AX4210 photoresist is spun on at 4000 rpm. This is followed by a soft bake at 75$^\circ$C for 30 minutes. The photoresist is exposed through a visually translucent iron oxide mask for 30 seconds using a Carl Zeuss mask aligner with 300 nm optics. To facilitate the lift-off process, the wafer is soaked in chlorobenzene for 10 minutes at 25$^\circ$C and blown dry with $N_2$. This is followed by a second bake at 90$^\circ$C for 10 minutes. The wafer is developed for about 2 minutes in 4:1 deionized $H_2O$:AZ400K developer, rinsed in deionized $H_2O$ for 5 minutes, and blown dry with $N_2$. Metalization consists of evaporating a 150 Angstrom adhesion layer followed by 1.8 $\mu$m of Ag followed by a 500 Angstrom Au cap. The wafer is then soaked in acetone until the metal lifts off.
It is advantageous to etch the ferroelectric from all regions except the coupled lines so that the bias tees are insensitive to tuning. A dilute 5 percent HF solution has been used to etch a Ba$_x$Sr$_{1-x}$TiO$_3$ rectangular mesa beneath the coupled sections. The tradeoff is that positioning the pattern over a good region of material is tougher.

The performance of these devices is measured using a HP 8510C automatic network analyzer. The device is paced in a simple test fixture with SMA connectors and usually the launchers are attached to the microstrip input and output with silver pint. Measurements are usually done in a vacuum of about 10 mT to prevent dielectric breakdown of the air between the coupled lines. Alternatively, paraffin can be used to coat the lines but occasionally air bubbles trapped inside may contribute to arcing. In the future, a spray coated Teflon coating will be used to permit safe operation under ambient conditions. Coupled microstripline FE phase shifters capitalize on the odd mode propagation constant and so have much more phase shift per unit length than simple microstrip while avoiding the need for a coplanar ground. Microwave measurements of coupled microstripline phase shifters of epitaxial Ba$_{0.5}$Sr$_{0.5}$TiO$_3$ films grown by combustion chemical vapor deposition (CCVD) on 0.5 mm MgO showed very low loss (estimated $\tan \delta$ was between 0.03-0.002 at 20 GHz at 23°C) [9]. As shown in figures 4 and 5, the transmission coefficient, $S_{21}$, at all frequencies exhibits symmetrical curve as a function of bias voltage at 297 K, as expected. The best figure of merit was 53°/dB [79]. It is evident that the hysteresis is negligible.

The best films have been deposited by laser ablation at temperatures between 650° and 750° C and a dynamic oxygen pressure near 100 mTorr [10,11]. Thicker Ba$_x$Sr$_{1-x}$TiO$_3$ films (>350 nm) generally exhibited poorer microwave performance despite having a clear theoretical advantage in terms of maximizing tuning as discussed in the next section. Crystalline quality unfortunately degrades as film thickness increases. The degradation is faster in Ba$_x$Sr$_{1-x}$TiO$_3$ than in SrTiO$_3$.

The use of MgO ($\epsilon_r$=9.7) allows wider lines for a given impedance compared to LaAlO$_3$ ($\epsilon_r$=24). Consequently, the conductor loss is lower on MgO. Figures 6 and 7 show measured insertion loss and phase for 0.5 µm Ba$_{0.6}$Sr$_{0.4}$TiO$_3$ film grown on 0.5 mm MgO. Choosing an operating temperature that approaches the Curie temperature from the paraelectric phase usually results in larger phase shifts but correspondingly higher loss.

![Figure 4. Measured 50 Ω 4-section phase shifter on MgO at 297 K. The Ba$_{0.50}$Sr$_{0.50}$TiO$_3$ film was grown by MicroCoating Technologies using CCVD.](image)
Figure 5. Measured insertion phase corresponding to figure 4.

Figure 6. Measured 50 Ohm 4-element coupled line phase shifter at 210 K with Au/Cr electrodes patterned on a 0.5 μm Ba0.6Sr0.4TiO3 film grown on 0.5 mm MgO. The film was grown by the Naval Research Laboratory. These film were 1 percent Mn doped and annealed at 1100° C for 6 hours.
The best performance to date has been obtained from $\text{YBa}_2\text{Cu}_3\text{O}_{7-\delta}$ and laser ablated $\text{SrTiO}_3$ films on (100) single crystal LaAlO$_3$ substrates [12]. Data for an 8-section nominally 50 $\Omega$ coupled microstrip device at 16 GHz is shown in figure 8. The superconducting film was 350 nm thick and the ferroelectric film was 2.0 $\mu$m thick. A figure of merit approaching the goal of $120^\circ$/dB was obtained. It is unclear what role surface effects may have played in the superior performance of this particular phase shifter that used $\text{YBa}_2\text{Cu}_3\text{O}_{7-\delta}$ electrodes instead of metal electrodes. Note that while bulk $\text{SrTiO}_3$ is an incipient ferroelectric, thin films exhibit a relative dielectric constant maximum between 40 and 80 K.

Some recent results suggest that after extended voltage cycling an anomalous discontinuity in loss and phase occurs under certain bias and film growth conditions. The origin of this polarization change is not understood at this time. Fatiguening effects have been observed in ferroelectric films for DRAM applications, where occasionally micro-cracks occur to absorb the stress. Such effects are irreversible. The study of this phenomenon is ongoing.
DEVICE MODELING

The multi-layer structure has been analyzed using a computationally efficient variational method to calculate the even and odd mode capacitance [7,13]. If a quasi-TEM type of propagation is assumed the propagation constant and impedance can be completely determined from line capacitance. Since the cascaded coupled line circuit resembles a series of one-pole bandpass filters, as the dc bias increases, the dielectric constant of the BST film decreases, causing the passband to rise in frequency and the tan $\delta$ of the BST to decrease. The impedance matrix of the cascaded network can be derived by well-known coupled line theory using the superposition of even and odd mode excitation. Then an equivalent S-parameter model can be extracted and used to predict the pass-band characteristics of the phase shifter.

The bandwidth compression from tuning is evident in figure 9 which is data from an 8-section phase shifter on 0.3 mm MgO using a 400 nm Ba$_{0.6}$Sr$_{0.4}$TiO$_3$ laser ablated film. The roll-off at the upper end of the frequency range is attributed to bias-tee effects.

In order to gauge the impact of the ferroelectric film on overall performance, Table 1 summarizes several important parameters for a single coupled microstrip section on $h_2$=0.3 mm MgO ($\varepsilon$=9.7) derived using the quasi-TEM analysis where $\varepsilon_1$ and $h_1$ correspond to figure 2. The insertion phase is designated as $\phi_i$, the composite dielectric loss as $\alpha_d$, and the characteristic impedance is taken as $Z_0=[Z_{eo}Z_{oo}]^{1/2}$. In all cases the loss tangent of the host substrate was 0.001 and the loss tangent of the ferroelectric film of thickness $h_1$ was taken as 0.05, 0.028, and 0.005 for $\varepsilon_1$ equal to 2500, 1000, and 500, respectively.

Figure 9. Measured Insertion Loss (including SMA launchers) of an 8-element =50 $\Omega$ PLD coupled microstripline phase shifter at 290 K as a function of bias voltage. Substrate is 0.3 mm MgO with 400 nm Ba$_{0.6}$Sr$_{0.4}$TiO$_3$ film. $l=350 \mu$m, $s=7.5 \mu$m and $w=30 \mu$m. Bandwidth compression from the filtering effect is evident. Marker 1, 2, 3, and 4 are at -5.75, -5.38, -6.00, and -6.49 dB, respectively.
Table 1. Theoretical propagation characteristics of a single coupled microstrip section on 0.3 mm MgO based on the quasi-TEM method described in [7] and [13]. \( l=350 \mu m, \ s=10 \mu m, \) and \( w=30 \mu m. \)

<table>
<thead>
<tr>
<th>( \varepsilon_1 )</th>
<th>( h_1 = 2 \mu m )</th>
<th>( h_1 = 1 \mu m )</th>
<th>( h_1 = 0.5 \mu m )</th>
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<td></td>
<td>( \phi_1 ° )</td>
<td>( \alpha_d ) (Np/m)</td>
<td>( Z_0 (\Omega) )</td>
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<tr>
<td>2500</td>
<td>65.9</td>
<td>66.3</td>
<td>29.7</td>
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<tr>
<td>1000</td>
<td>46.6</td>
<td>22.5</td>
<td>40.7</td>
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<tr>
<td>500</td>
<td>37.3</td>
<td>3.0</td>
<td>49.7</td>
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The net phase shift is 2.2 times greater for the 2 \( \mu m \) film compared to the 500 nm film. Table 2 summarizes propagation characteristics for a single coupled microstrip section on \( h_2=0.25 \) mm LaAlO\(_3\) (\( \varepsilon=24 \)) derived using the quasi-TEM analysis. The insertion phase is greater because the effective permittivity of the composite structure is substantially greater than that of Table 1. But the correlation between phase shift and film thickness is about the same.

Table 2. Theoretical propagation characteristics of a single coupled microstrip section on 0.25 mm LaAlO\(_3\) based on the quasi-TEM method described in [7] and [13]. \( l=457 \mu m, \ s=8 \mu m, \) and \( w=25 \mu m. \)

<table>
<thead>
<tr>
<th>( \varepsilon_1 )</th>
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<td>( \phi_1 ° )</td>
<td>( \alpha_d ) (Np/m)</td>
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<td>2500</td>
<td>100.1</td>
<td>70.4</td>
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<td>1000</td>
<td>73.9</td>
<td>23.9</td>
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<tr>
<td>500</td>
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It is clear from the experimental and modeled data that the inherent dielectric loss of epitaxial ferroelectric films isn't necessarily devastating insofar as microwave device performance is concerned. Indeed the loss tangent of a thin dielectric film \( (h_1 \leq 2 \mu m) \) on a good substrate \( (\tan \delta \leq 0.001) \) can deteriorate substantially \( (\tan \delta \leq 0.05) \) before the insertion loss of the structures presented here is compromised. Even when the bulk of the substrate has relatively high loss, useful devices can be rendered for certain applications. Microwave designers generally quote a loss tangent of \( 10^{-4} \) as desirable. But as can be seen from figure 10, a loss tangent as poor as \( 10^{-2} \) translates into an insertion loss of only 1 dB at 18 GHz for a 1 cm long 50 \( \Omega \) microstrip line on a homogeneous substrate.

Figures 11 and 12 represent simulated S-parameter data comparing the effect of loss tangent, using IE3D software, for the 8-section ferroelectric phase shifter corresponding to figure 9. IE3D uses a method of moments based solution and has been found to be very accurate when compared to experiment for these multi-layer structures. In both graphs the \( \tan \delta \) of the MgO was \( 10^{-4} \).
Figure 10. Simulated effect (using IE3D) of substrate loss tangent on insertion loss of a 1 cm long 50 Ω microstrip line terminated in a matched source and load on 0.25 mm LaAlO₃. The 2 μm thick metal strip and ground plane had an electrical conductivity of $4.9 \times 10^7$ S/m.

Figure 11. Modeled S-parameters for an 8-section coupled microstrip ferroelectric phase shifter on 0.3 mm MgO with 400 nm $\text{Ba}_{0.60}\text{Sr}_{0.40}\text{TiO}_3$ film. $l=350 \text{ μm}$, $s=7.5 \text{ μm}$ and $w=30 \text{ μm}$. $\varepsilon_r=2500$, $\tan\delta=0.05$, and $\sigma=4.9 \times 10^7$ S/m for the 2.5 μm metal layers.
The difference in $S_{21}$ was about 1.25 dB when the effect of $\tan \delta$ is considered, in this particular case. The loss due to impedance mismatch is about 0.5 dB or less for the zero field condition but can degrade to 1 dB or more if the ferroelectric is tuned to $\varepsilon_r=300$. Conductor loss is evidently about 1 dB and radiation is considered negligible since the lines are intentionally operated in the odd mode. In this mode the currents in the coupled lines are equal but opposite so the radiated fields tend to cancel. The overall loss is ideally 3.5 to 4.0 dB when the phase shifters are embedded between a 50 Ω source and load.

It is fundamentally important to ensure that a good conductor with the proper thickness is used for the electrodes and ground plane. Figure 13 illustrates the difference between the measured resistivity of a thin gold film and bulk gold. Since the conductor loss is proportional to surface resistance, there can be a dramatic impact on loss if the conductor isn’t at least several skin depths thick. And the proper value for resistivity must be used. For example, for a single section coupled line on 0.3 mm MgO and using the thin film resistivity values from figure 13, the insertion loss at 19 GHz and 290 K for 1.0 μm and 2.5 μm thick gold electrodes is 0.63 dB and 0.48 dB, respectively. Hence an excess loss of 1 dB per 8-section phase shifter can easily occur from improper lithography. Some of the experimental phase shifter data provided earlier may have suffered from this effect.
Figure 13. Comparison between resistivity of a thin evaporated Au film on Al2O3 and bulk Au as a function of temperature.

CONCLUSIONS

Coupled microstrip line ferroelectric phase shifters have already demonstrated performance superior to their semiconductor counterparts at microwave frequencies. Typical de-embedded insertion loss for these novel $\approx 360^\circ$ phase shifters is about 5 dB. But in order to realize the full technical and economic benefits of a new type of phased array antenna, called the ferroelectric reflectarray, a 3 dB insertion loss ferroelectric phase shifter must be produced on a consistent basis. Incorporating a microstrip matching network between the coupled sections and the terminations can potentially produce a 0.5 to 1 dB improvement. Lower characteristic impedance devices could reduce conductor loss even further. And the deposition of dense, high conductivity electrodes that are at least $\approx 3$ skin depths thick can result in further improvement. If the tan$\delta$ of the ferroelectric film could be maintained at 0.005 or less, the films contribution to total loss would be essentially negligible except for the mismatch it introduces as it is tuned. But even a tan$\delta$ of $<0.05$ is manageable. It is most desirable to maintain the crystalline properties of the ferroelectric films to a thickness of at least 1 $\mu$m. Relatively thick films increase the phase shift per coupled section while the conductor loss stays more or less constant. Consequently the number of sections required to produce a full $360^\circ$ phase shift can be reduced.
REFERENCES
### Analysis and Optimization of Thin Film Ferroelectric Phase Shifters

**Title and Subtitle**

Microwave phase shifters have been fabricated from (YBa$_2$Cu$_3$O$_{7-δ}$ or Au)/SrTiO$_3$ and Au/Ba$_x$Sr$_{1-x}$TiO$_3$ films on LaA1O$_3$ and MgO substrates. These coupled microstrip devices rival the performance of their semiconductor counterparts at Ku- and K-band frequencies. Typical insertion loss for room temperature ferroelectric phase shifters at K-band is $\approx 5$ dB. An experimental and theoretical investigation of these novel devices explains the role of the ferroelectric film in overall device performance. A roadmap to the development of a 3 dB insertion loss phase shifter that would enable a new type of phased array antenna is discussed.

**Subject Terms**

Phased array; Antennas